

**BID RELEASE**

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## **Fii High Performance Computing Data Center Bid Package #02 – Site Utilities, Waterproofing, Elevators**



**The Site Utilities, Waterproofing, Elevators Bid Package #02 for the Fii High Performance Computing Data Center is now available.**

### **BID PACKAGE #02 – Site Utilities, Waterproofing, Elevators**

Contract No. 06	Site Utilities
Contract No. 07	Waterproofing
Contract No. 08	Elevators

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## **Fii High Performance Computing Data Center Bid Package #02**



### **Non-Disclosure Agreement – NDA:**

The Mortenson NDA must be signed and returned to Mortenson to participate in this bid invitation. The NDA will be issued through our Building Connected website after any firm registers through the link provided below.

### **About the Project:**

The project consists of construction of the Fii High Performance Computing Data Center. This includes a 11,000 SF data center office and 34,000 SF data center equipment shed.

Procurement of Subcontractors, Suppliers, Vendors, and Professional Services will follow the clear and detailed process of the Wisconsin First program.

### **Registration and Bid Information:**

To receive project information, please register via the link below:

<https://bit.ly/2k9Qn5V>

After your firm has registered, a Building Connected invitation will be emailed to the email address provided within one business day. If you do not receive the invitation or have trouble, please email both [denise.farhnow@mortenson.com](mailto:denise.farhnow@mortenson.com) and [ross.bunchek@mortenson.com](mailto:ross.bunchek@mortenson.com)

A pre-bid meeting will be held on October 31st. Information on location and date will be available after registering on the WisconnValley site and signing the NDA.

### **Information and Resources:**

[Wisconvalley.wi.gov](http://Wisconvalley.wi.gov)